

U. S. Patent Application No. 09/767,922

IN THE CLAIMS:

Claim 1. (Currently amended) An image pickup device comprising:
a light-transmissible board formed from a light transmitting material, said board having a wiring pattern formed on one surface thereof and containing an optical filter disposed thereon for filtering light transmitted through the light transmitting material of the board; and

an image pickup element having a photodetecting portion formed on the same surface thereof, said image pickup element being mounted in flip-chip style on the one surface of said light-transmissible board so that the photodetecting portion of the image pickup element is opposed to an area where the wiring pattern is not formed;

wherein said wiring pattern is configured to match an electrode arrangement of said image pickup element and a terminal arrangement of a connector.

Claim 2. (Original) The image pickup device as claimed in claim 1, wherein said optical filter is an infrared rays cutting filter.

Claim 3. (Previously presented) The image pickup device as claimed in claim 1, wherein a peripheral edge portion of said image pickup element is sealed with resin.

Claim 4. (Currently amended) A camera module comprising:
a light-transmissible board formed from a light transmitting material having a wiring pattern formed on one surface thereof and containing an optical filter disposed thereon for filtering light transmitted through the light transmitting material of the board; and

an image pickup element having a photodetecting portion formed on the same surface thereof; and

a lens holder unit comprising a lens, said lens being mounted above the other surface of said light-transmissible board so as to be located above said photodetecting portion of said image pickup element, said image pickup element being mounted in a

flip-chip style on the one surface of said light-transmissible board so that the

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photodetecting portion of the image pickup element is opposed to an area where the wiring pattern is not formed;

wherein said wiring pattern is configured to match an electrode arrangement of said image pickup element and a terminal arrangement of a connector.

Claim 5. (Currently amended) A camera system using a camera module comprising:

a light-transmissible board formed from a light transmitting material having a wiring pattern formed on one surface thereof and containing an optical filter disposed thereon for filtering light transmitted through the light transmitting material of the board; and

an image pickup element having a photodetecting portion formed on the same surface thereof; and

a lens holder unit comprising a lens, said lens being mounted above the other surface of said light-transmissible board so as to be located above said photodetecting portion of said image pickup element, said image pickup element being mounted in flip-chip style on the one surface of said light-transmissible board so that the photodetecting portion of the image pickup element is confronted to a wiring-pattern non-forming area;

wherein said wiring pattern is configured to match an electrode arrangement of said image pickup element and a terminal arrangement of a connector.